



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-11-05
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8M42*F125AFG	A	Z6HA	2015-11-05
Amount	UoM	Unit type	ST ECOPACK Grade	
73.90	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	5x5x1	32	gull wing	
Comment	Package: VFQFPN 5X5x1.0 32L PITCH 0.5; MDF valid for STWBC; STWBCTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8M42*F125AFG					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	6.883	mg	supplier	die	Silicon (Si)	7440-21-3		6.514	mg	959211	88146
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.024	mg	3534	325
Die				supplier	metallization	Copper (Cu)	7440-50-8		0.08	mg	11780	1083
Die				supplier	metallization	Tantalum (Ta)	7440-25-7		0.009	mg	1325	122
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.012	mg	1767	162
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	147	14
Die				supplier	Passivation	Silicon Nitride	12033-89-5		0.021	mg	3092	284
Die				supplier	Passivation	Silicon Oxide	7631-86-9		0.13	mg	19143	1759
Leadframe	Copper & its alloys	19.902	mg	supplier	alloy	Copper (Cu)	7440-50-8		19.454	mg	972311	263248
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.444	mg	22191	6008
Leadframe				supplier	alloy	Phosphorus (P)	12185-10-3		0.007	mg	350	95
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.027	mg	1349	365
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.073	mg	3649	988
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	100	27
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	50	14
Die attach	Other inorganic materials	4.762	mg	supplier	glue	Silver (Ag)	7440-22-4		3.274	mg	683793	44303
Die attach				supplier	glue	methylene diacrylate	42594-17-2		1.197	mg	250000	16198
Die attach				supplier	glue	Dicyclopentenylxyethyl methacrylate	68586-19-6		0.144	mg	30075	1949
Die attach				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.144	mg	30075	1949
Die attach				supplier	glue	Palladium (Pd)	7440-05-3		0.005	mg	1044	68
Die attach				supplier	glue	Bis(α , α -dimethylbenzyl) peroxide	80-43-3		0.024	mg	5013	325
Bonding wires	Precious metals	0.435	mg	supplier	wire	Gold (Au)	7440-57-5		0.423	mg	990632	5724
Bonding wires				supplier	wire	Palladium (Pd)	7440-05-3		0.004	mg	9368	54
Encapsulation	Other Organic Materials	41.662	mg	supplier	mold compound	Silica, vitreous	60676-86-0		38.786	mg	925990	524844
Encapsulation				supplier	mold compound	epoxy resin	85954-11-6		1.676	mg	40013	22679
Encapsulation				supplier	mold compound	phenol resin	26834-02-6		1.257	mg	30010	17009
Encapsulation				supplier	mold compound	carbon black	1333-86-4		0.167	mg	3987	2260